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[Samsung Electro-Mechanics America, Inc.](#)
[CL21A475KPCLNNC](#)

For any questions, you can email us directly:

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SAMSUNG
ELECTRO-MECHANICS



SPECIFICATION

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor

- Samsung P/N : **CL21A475KPCLNNC**
- Description : **CAP, 4.7 μ F, $\pm$ 10%, 10V, X5R, 0805**

A. Samsung Part Number

CL 21 A 475 K P C L N N C
 ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

① Series	Samsung Multi-layer Ceramic Capacitor									
② Size	0805 (inch code)	L: 2.0 $\pm$ 0.1 mm	W: 1.25 $\pm$ 0.1 mm							
③ Dielectric	X5R	⑧ Thickness division		Low profile						
④ Capacitance	4.7 μ F	⑧ Inner electrode		Ni						
⑤ Capacitance tolerance	$\pm$ 10 %	⑧ Termination		Cu						
⑥ Rated Voltage	10 V	⑧ Plating		Sn 100% (Pb Free)						
⑦ Thickness	0.85 $\pm$ 0.1 mm	⑨ Product		Normal						
		⑩ Special		Reserved for future use						
		⑪ Packaging		Cardboard Type, 7" reel						

B. Samsung Reliability Test and Judgement condition

	Performance	Test condition
Capacitance	Within specified tolerance	1kHz $\pm$ 10% 1.0 $\pm$ 0.2Vrms
Tan δ (DF)	0.1 max.	
Insulation Resistance	10,000Mohm or 100Mohm $\cdot\mu$ F Whichever is Smaller	Rated Voltage 60~120 sec.
Appearance	No abnormal exterior appearance	Microscope ($\times$ 10)
Withstanding Voltage	No dielectric breakdown or mechanical breakdown	250% of the rated voltage
Temperature Characterisitcs	X5R (From -55 $^{\circ}$ C to 85 $^{\circ}$ C, Capacitance change should be within $\pm$ 15%)	
Adhesive Strength of Termination	No peeling shall be occur on the terminal electrode	500g-F, for 10 $\pm$ 1 sec.
Bending Strength	Capacitance change : within $\pm$ 12.5%	Bending to the limit (1mm) with 1.0mm/sec.
Solderability	More than 75% of terminal surface is to be soldered newly	SnAg3.0Cu0.5 solder 245 $\pm$ 5 $^{\circ}$ C, 3 $\pm$ 0.3sec. (preheating : 80~120 $^{\circ}$ C for 10~30sec.)
Resistance to Soldering heat	Capacitance change : within $\pm$ 7.5% Tan δ , IR : initial spec.	Solder pot : 270 $\pm$ 5 $^{\circ}$ C, 10 $\pm$ 1sec.

	Performance	Test condition
Vibration Test	Capacitance change : within $\pm 5\%$ Tan δ , IR : initial spec.	Amplitude : 1.5mm From 10Hz to 55Hz (return : 1min.) 2hours $\times$ 3 direction (x, y, z)
Moisture Resistance	Capacitance change : within $\pm 12.5\%$ Tan δ : 0.125 max IR : 12.5M $\Omega \cdot \mu F$ or Over	With rated voltage 40 $\pm 2^\circ\text{C}$, 90~95%RH, 500+12/-0hrs
High Temperature Resistance	Capacitance change : within $\pm 12.5\%$ Tan δ : 0.125 max IR : 25M $\Omega \cdot \mu F$ or Over	With 150% of the rated voltage Max. operating temperature 1000+48/-0hrs
Temperature Cycling	Capacitance change : within $\pm 7.5\%$ Tan δ , IR : initial spec.	1 cycle condition Min. operating temperature $\rightarrow 25^\circ\text{C}$ $\rightarrow$ Max. operating temperature $\rightarrow 25^\circ\text{C}$ 5 cycle test

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 $^\circ\text{C}$, 10sec. Max)

* For the more detail Specification, Please refer to the Samsung MLCC catalogue.